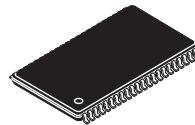




64K x 16-Bit 3.3-V Asynchronous Magnetoresistive RAM

MR0A16A



44-TSOP
Case 924A-02

Introduction

The MR0A16A is a 1,048,576-bit magnetoresistive random access memory (MRAM) device organized as 65,536 words of 16 bits. The MR0A16A is equipped with chip enable (\overline{E}), write enable (\overline{W}), and output enable (\overline{G}) pins, allowing for significant system design flexibility without bus contention. Because the MR0A16A has separate byte-enable controls (\overline{LB} and \overline{UB}), individual bytes can be written and read.

MRAM is a nonvolatile memory technology that protects data in the event of power loss and does not require periodic refreshing. The MR0A16A is the ideal memory solution for applications that must permanently store and retrieve critical data quickly.

The MR0A16A is available in a 400-mil, 44-lead plastic small-outline TSOP type-II package with an industry-standard center power and ground SRAM pinout.

The MR0A16A is available in Commercial (0°C to 70°C), Industrial (-40°C to 85°C) and Extended (-40°C to 105°C) ambient temperature ranges.

Features

- Single 3.3-V power supply
- Commercial temperature range (0°C to 70°C), Industrial temperature range (-40°C to 85°C) and Extended temperature range (-40°C to 105°C)
- Symmetrical high-speed read and write with fast access time (35 ns)
- Flexible data bus control — 8 bit or 16 bit access
- Equal address and chip-enable access times
- Automatic data protection with low-voltage inhibit circuitry to prevent writes on power loss
- All inputs and outputs are transistor-transistor logic (TTL) compatible
- Fully static operation
- Full nonvolatile operation with 20 years minimum data retention

This document contains information on a new product under development. Freescale reserves the right to change or discontinue this product without notice.

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Device Pin Assignment

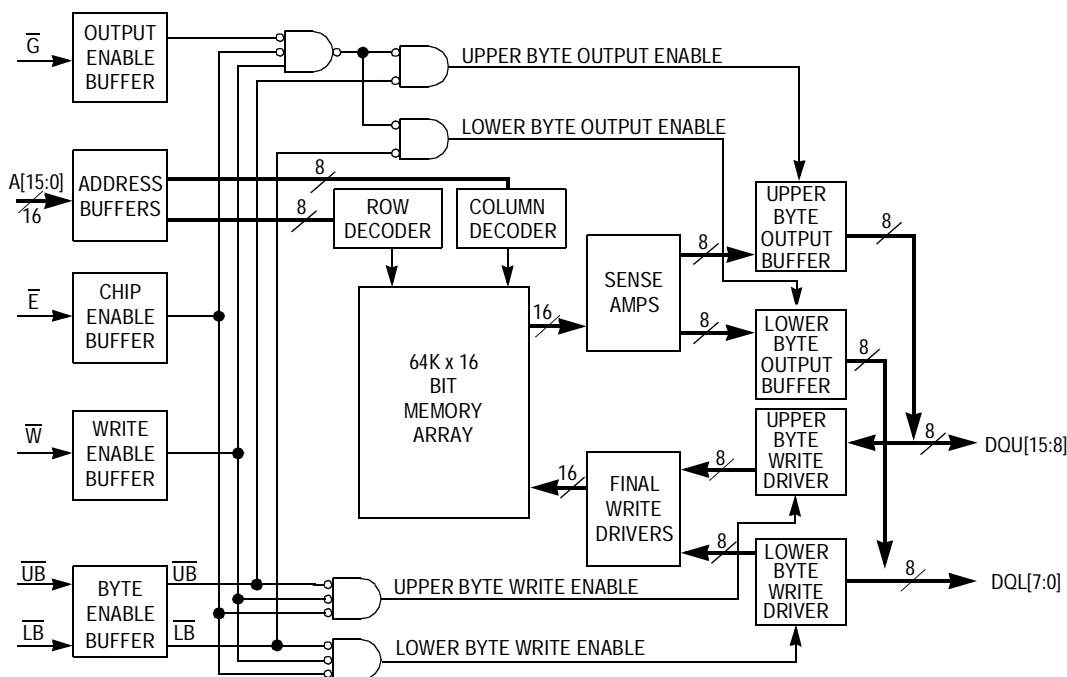


Figure 1. Block Diagram

Device Pin Assignment

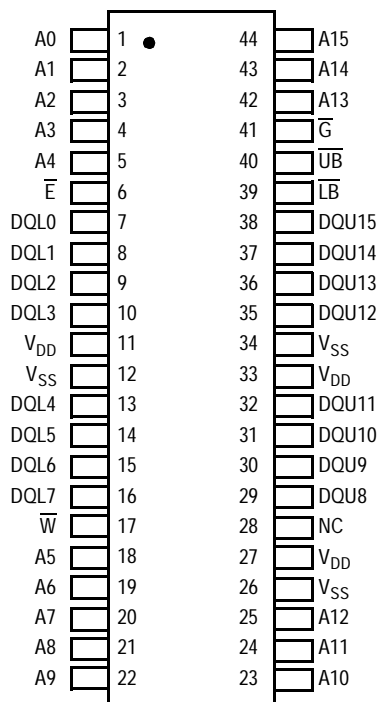


Table 1. Pin Functions

Signal Name	Function
A	Address input
\bar{E}	Chip enable
\bar{W}	Write enable
\bar{G}	Output enable
\bar{UB}	Upper byte select
\bar{LB}	Lower byte select
DQL	Data I/O, lower byte
DQU	Data I/O, upper byte
V_{DD}	Power supply
V_{SS}	Ground
NC	Do not connect this pin

Figure 2. MR0A16A in 44-Pin TSOP Type II Package

Table 2. Operating Modes

\overline{E}^1	\overline{G}^1	\overline{W}^1	\overline{LB}^1	\overline{UB}^1	Mode	V_{DD} Current	DQL[7:0] ²	DQU[15:8] ²
H	X	X	X	X	Not selected	I_{SB1}, I_{SB2}	Hi-Z	Hi-Z
L	H	H	X	X	Output disabled	I_{DDR}	Hi-Z	Hi-Z
L	X	X	H	H	Output disabled	I_{DDR}	Hi-Z	Hi-Z
L	L	H	L	H	Lower byte read	I_{DDR}	D_{Out}	Hi-Z
L	L	H	H	L	Upper byte read	I_{DDR}	Hi-Z	D_{Out}
L	L	H	L	L	Word read	I_{DDR}	D_{Out}	D_{Out}
L	X	L	L	H	Lower byte write	I_{DDW}	D_{In}	Hi-Z
L	X	L	H	L	Upper byte write	I_{DDW}	Hi-Z	D_{In}
L	X	L	L	L	Word write	I_{DDW}	D_{In}	D_{In}

NOTES:

- ¹ H = high, L = low, X = don't care
- ² Hi-Z = high impedance

Electrical Specifications
Absolute Maximum Ratings

This device contains circuitry to protect the inputs against damage caused by high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage greater than maximum rated voltages to these high-impedance (Hi-Z) circuits.

The device also contains protection against external magnetic fields. Precautions should be taken to avoid application of any magnetic field more intense than the maximum field intensity specified in the maximum ratings.

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Table 3. Absolute Maximum Ratings¹

Parameter	Symbol	Value	Unit
Supply voltage ²	V _{DD}	-0.5 to 4.0	V
Voltage on any pin ²	V _{In}	-0.5 to V _{DD} + 0.5	V
Output current per pin	I _{Out}	±20	mA
Package power dissipation ³	P _D	0.600	W
Temperature under bias MR0A16AYS35 (Commercial) MR0A16ACYS35 (Industrial) MR0A16AVYS35 (Extended)	T _{Bias}	-10 to 85 -45 to 95 -45 to 110	°C
Storage temperature	T _{stg}	-55 to 150	°C
Lead temperature during solder (3 minute max)	T _{Lead}	260	°C
Maximum magnetic field during write MR0A16AYS35 (Commercial) MR0A16ACYS35 (Industrial) MR0A16AVYS35 (Extended)	H _{max_write}	15 25 25	Oe
Maximum magnetic field during read or standby	H _{max_read}	100	Oe

NOTES:

- Permanent device damage may occur if absolute maximum ratings are exceeded. Functional operation should be restricted to recommended operating conditions. Exposure to excessive voltages or magnetic fields could affect device reliability.
- All voltages are referenced to V_{SS}.
- Power dissipation capability depends on package characteristics and use environment.

Table 4. Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Power supply voltage	V _{DD}	3.0 ¹	3.3	3.6	V
Write inhibit voltage	V _{WI}	2.5	2.7	3.0 ¹	V
Input high voltage	V _{IH}	2.2	—	V _{DD} + 0.3 ²	V
Input low voltage	V _{IL}	-0.5 ³	—	0.8	V
Operating temperature MR0A16AYS35 (Commercial) MR0A16ACYS35 (Industrial) MR0A16AVYS35 (Extended)	T _A	0 -40 -40		70 85 105	°C

NOTES:

- After power up or if V_{DD} falls below V_{WI}, a waiting period of 2 ms must be observed, and \bar{E} and \bar{W} must remain high for 2 ms. Memory is designed to prevent writing for all input pin conditions if V_{DD} falls below minimum V_{WI}.
- V_{IH} (max) = V_{DD} + 0.3 Vdc; V_{IH} (max) = V_{DD} + 2.0 Vac (pulse width ≤ 10 ns) for I ≤ 20.0 mA.
- V_{IL} (min) = -0.5 Vdc; V_{IL} (min) = -2.0 Vac (pulse width ≤ 10 ns) for I ≤ 20.0 mA.

Timing Specifications
Read Mode**Table 9. Read Cycle Timing**^{1, 2}

Parameter	Symbol	Min	Max	Unit
Read cycle time	t _{AVAV}	35	—	ns
Address access time	t _{AVQV}	—	35	ns
Enable access time ³	t _{ELQV}	—	35	ns
Output enable access time	t _{GLQV}	—	15	ns
Byte enable access time	t _{BLQV}	—	15	ns
Output hold from address change	t _{AXQX}	3	—	ns
Enable low to output active ^{4, 5}	t _{ELQX}	3	—	ns
Output enable low to output active ^{4, 5}	t _{GLQX}	0	—	ns
Byte enable low to output active ^{4, 5}	t _{BLQX}	0	—	ns
Enable high to output Hi-Z ^{4, 5}	t _{EHQZ}	0	15	ns
Output enable high to output Hi-Z ^{4, 5}	t _{GHQZ}	0	10	ns
Byte high to output Hi-Z ^{4, 5}	t _{BHQZ}	0	10	ns

NOTES:

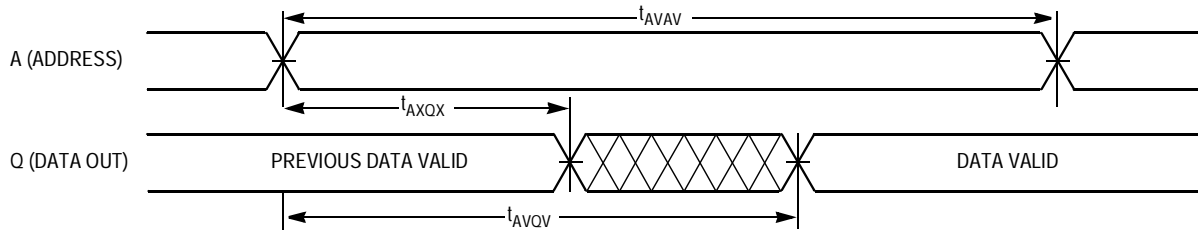
¹ \bar{W} is high for read cycle.

² Due to product sensitivities to noise, power supplies must be properly grounded and decoupled, and bus contention conditions must be minimized or eliminated during read and write cycles.

³ Addresses valid before or at the same time \bar{E} goes low.

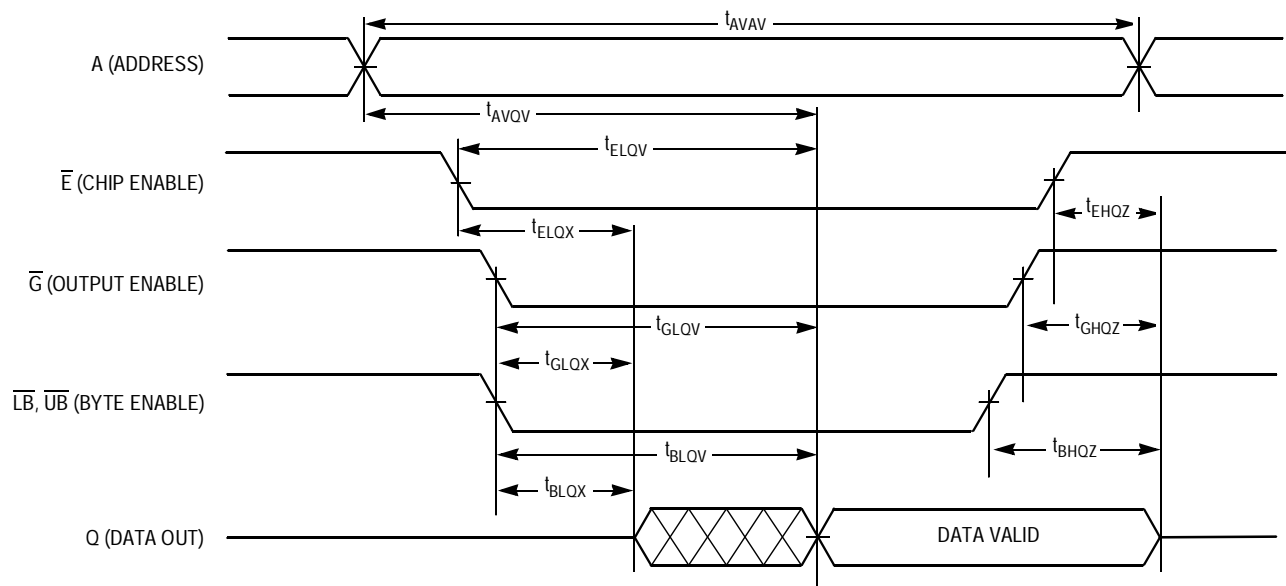
⁴ This parameter is sampled and not 100% tested.

⁵ Transition is measured ±200 mV from steady-state voltage.



NOTES:

Device is continuously selected ($\bar{E} \leq V_{IL}, \bar{G} \leq V_{IL}$).

Figure 4. Read Cycle 1

Figure 5. Read Cycle 2

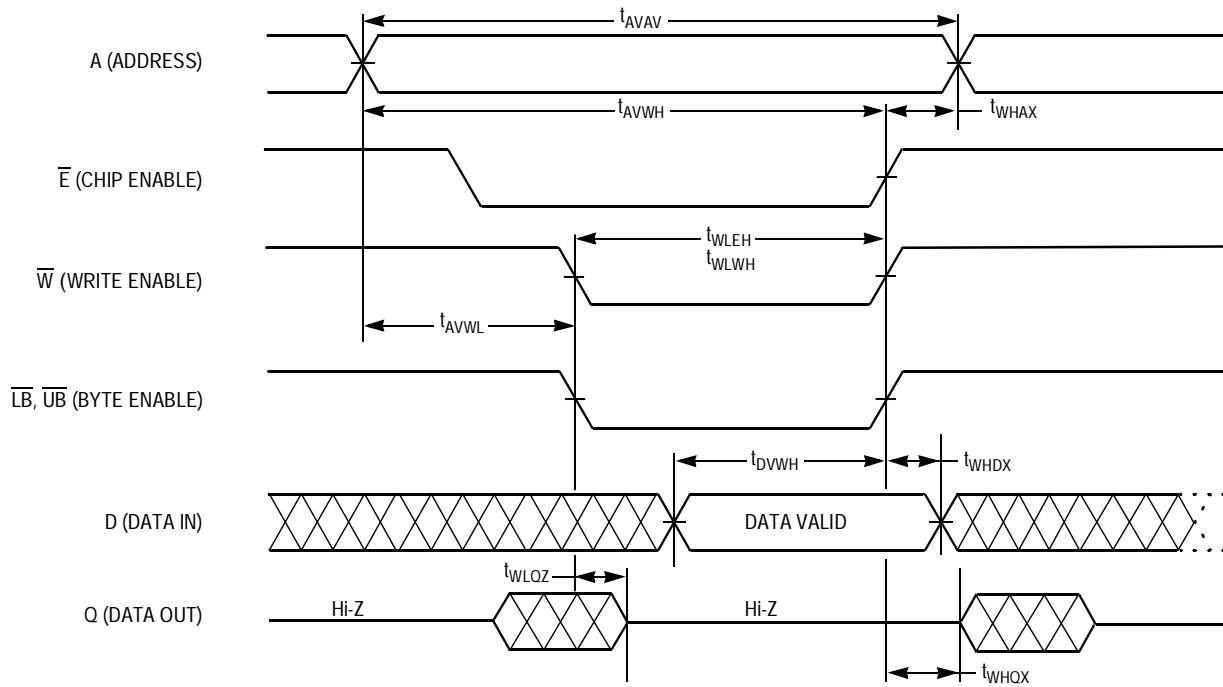


Figure 6. Write Cycle 1 (\bar{W} Controlled)

Table 11. Write Cycle Timing 2 (\overline{E} Controlled)^{1, 2, 3, 4, 5}

Parameter	Symbol	Min	Max	Unit
Write cycle time ⁶	t_{AVAV}	35	—	ns
Address set-up time	t_{AVEL}	0	—	ns
Address valid to end of write (\overline{G} high)	t_{AVEH}	18	—	ns
Address valid to end of write (\overline{G} low)	t_{AVEH}	20	—	ns
Enable to end of write (\overline{G} high)	t_{ELEH} t_{ELWH}	15	—	ns
Enable to end of write (\overline{G} low) ^{7, 8}	t_{ELEH} t_{ELWH}	15	—	ns
Data valid to end of write	t_{DVEH}	10	—	ns
Data hold time	t_{EHDX}	0	—	ns
Write recovery time	t_{EHAX}	12	—	ns

NOTES:

- ¹ A write occurs during the overlap of \overline{E} low and \overline{W} low.
- ² Due to product sensitivities to noise, power supplies must be properly grounded and decoupled and bus contention conditions must be minimized or eliminated during read and write cycles.
- ³ If \overline{G} goes low at the same time or after \overline{W} goes low, the output will remain in a high-impedance state.
- ⁴ After \overline{W} , \overline{E} , or $\overline{UB/LB}$ has been brought high, the signal must remain in steady-state high for a minimum of 2 ns.
- ⁵ The minimum time between \overline{E} being asserted low in one cycle to \overline{E} being asserted low in a subsequent cycle is the same as the minimum cycle time allowed for the device.
- ⁶ All write cycle timings are referenced from the last valid address to the first transition address.
- ⁷ If \overline{E} goes low at the same time or after \overline{W} goes low, the output will remain in a high-impedance state.
- ⁸ If \overline{E} goes high at the same time or before \overline{W} goes high, the output will remain in a high-impedance state.

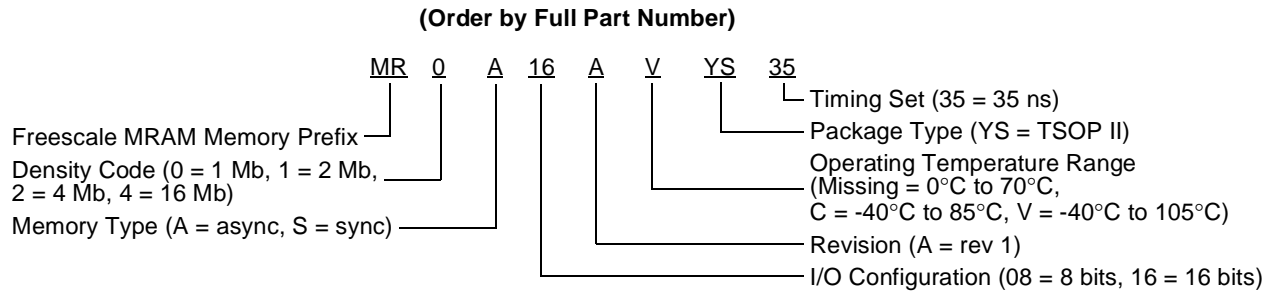
Ordering Information

This product is available in Commercial, Industrial, and Extended temperature versions.

Freescale's semiconductor products can be classified into the following tiers: "Commercial", "Industrial" and "Extended." A product should only be used in applications appropriate to its tier as shown below. For questions, please contact a Freescale sales representative.

- **Commercial** — Typically 5 year applications - personal computers, PDA's, portable telecom products, consumer electronics, etc.
- **Industrial, Extended** — Typically 10 year applications - installed telecom equipment, workstations, servers, etc. These products can also be used in Commercial applications.

Part Numbering System



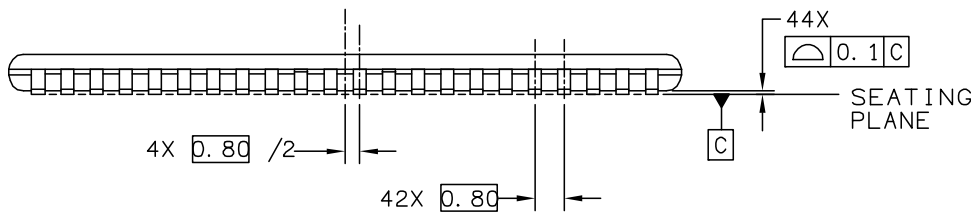
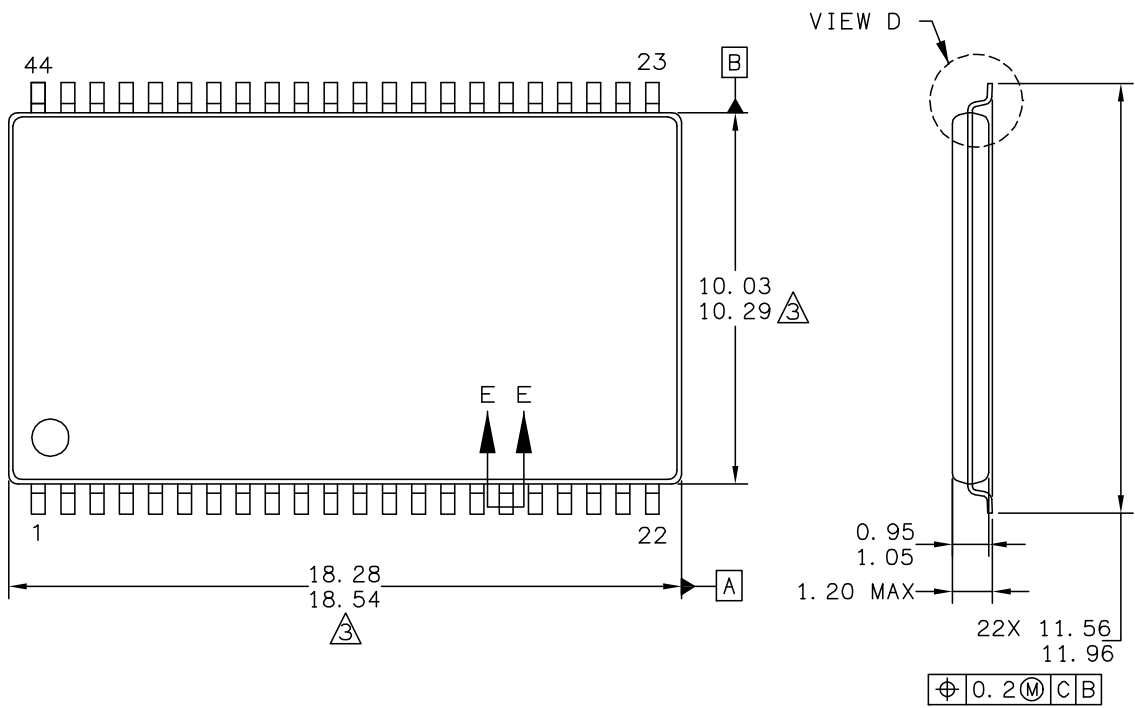
Package Information

Table 13. Package Information

Device	Pin Count	Package Type	Designator	Case No.	Document No.	RoHS Compliant
MR0A16A	44	TSOP Type II	YS	924A-02	98ASS23673W	True

Mechanical Drawing

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		DOCUMENT NO: 98ASS23673W	REV: C
TITLE: 44 LEAD TSOP, TYPE II, .400 WIDE	CASE NUMBER: 924A-02	17 MAY 2005	
	STANDARD: NON-JEDEC		

NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M – 1994.

2. DIMENSIONS IN MILLIMETERS.

$\triangle 3$ DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION.
ALLOWABLE MOLD PROTRUSION IS 0.15 PER SIDE.

$\triangle 4$ DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSIONS.
DAM BAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH
TO EXCEED 0.58.

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TITLE: 44 LEAD TSOP, TYPE II, .400 WIDE	DOCUMENT NO: 98ASS23673W	REV: C	
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